

Global 3D IC and 2.5D IC Packaging Market Research Report 2016

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Abstracts

Notes:

Production, means the output of 3D IC and 2.5D IC Packaging

Revenue, means the sales value of 3D IC and 2.5D IC Packaging

This report studies 3D IC and 2.5D IC Packaging in Global market, especially in North America, Europe, China, Japan, Korea and Taiwan, focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

Taiwan Semiconductor

Samsung Electronics

Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

Market Segment by Regions, this report splits Global into several key Regions, with production, consumption, revenue, market share and growth rate of 3D IC and 2.5D IC Packaging in these regions, from 2011 to 2021 (forecast), like

North America

Europe

China

Japan

Korea

Taiwan

Split by product type, with production, revenue, price, market share and growth rate of each type, can be divided into

3D wafer-level chip-scale packaging

3D TSV

2.5D

Split by application, this report focuses on consumption, market share and growth rate of 3D IC and 2.5D IC Packaging in each application, can be divided into

Logic

Imaging & optoelectronics

Memory

MEMS/sensors

LED

Power, analog & mixed signal, RF, photonics

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